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PATENT  
YOR19960184US1  
IBM-219

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

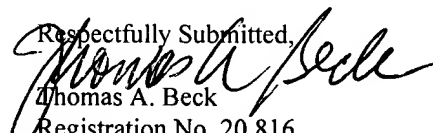
In re Application of : D.Y. Shih, et al.  
Serial Number : 09/254,769  
Filing Date : March 11, 1999  
Examiner : V. Nguyen  
Group Art Unit : 2829  
For :  
WAFER SCALE HIGH DENSITY  
PROBE ASSEMBLY, APPARATUS FOR  
USE THEREOF  
AND METHODS OF FABRICATION  
THEREOF

Honorable Commissioner of Patents  
and Trademarks  
Post Office Box 1450  
Alexandria, VA 22313-1450

Sir:

In response to the Official Action dated June 7, 2007, please cancel Figure 6(a) and remove same from the drawings to be issued in this application.

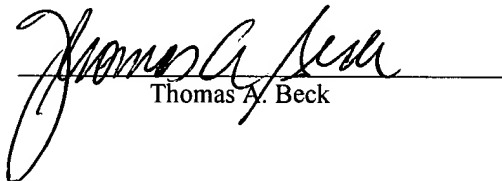
Please send all future communications in this application to the undersigned at 6136 West Kimberly Way, Glendale, AZ 85308-7627.

Respectfully Submitted,  
  
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CERTIFICATE OF MAILING

I hereby certify that this correspondence is being transmitted by the United States Postal Service, First Class mail postage prepaid on the date shown below to the United States Patent Office, Post Office Box 1450, Alexandria, VA 22313-1450.

July 7, 2007

  
Thomas A. Beck